

### APPLICATIONS

- High Frequency Applications
- Regulated Power Supplies
- Capacitor Discharge
- Ultrasonic Generators
- Induction Heating

### KEY PARAMETERS

$V_{DRM}$	<b>1800V</b>
$I_{T(AV)}$	<b>380A</b>
$I_{TSM}$	<b>6000A</b>
$dV/dt$	<b>1000V/<math>\mu</math>s</b>
$di/dt$	<b>500A/<math>\mu</math>s</b>
$t_q$	<b>10.0<math>\mu</math>s</b>

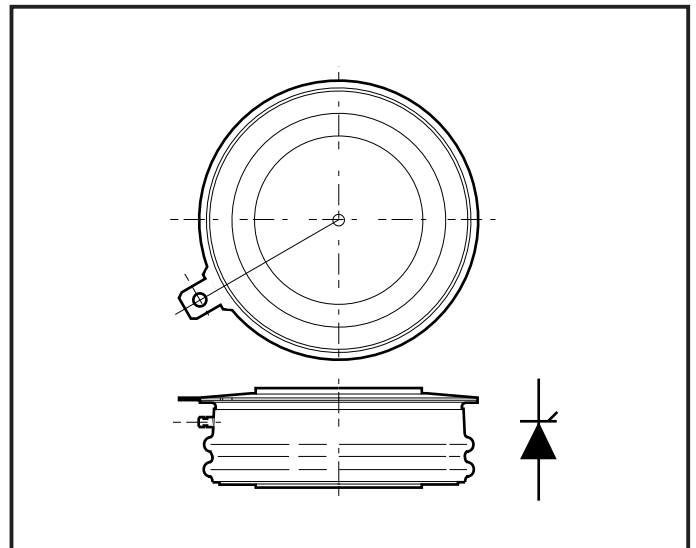
### FEATURES

- The ACR400SE is an asymmetric thyristor which has exceptionally fast turn-off capabilities combined with good turn-on characteristics.

### VOLTAGE RATINGS

Type Number	Repetitive Peak Off-state Voltage	Repetitive Peak Reverse Voltage
	$V_{DRM}$ V	$V_{RRM}$ V
ACR400SE18	1800	10
ACR400SE16	1600	10
ACR400SE14	1400	10
ACR400SE12	1200	10

Lower voltage grades available.



Outline type code: E.  
See Package Details for further information.

### CURRENT RATINGS

Symbol	Parameter	Conditions	Max.	Units
<b>Double Side Cooled</b>				
$I_{T(AV)}$	Mean on-state current	Half wave resistive load, $T_{case} = 80^{\circ}C$	380	A
$I_{T(RMS)}$	RMS value	$T_{case} = 80^{\circ}C$	600	A
$I_T$	Continuous (direct) on-state current	$T_{case} = 80^{\circ}C$	490	A
<b>Single Side Cooled (Anode side)</b>				
$I_{T(AV)}$	Mean on-state current	Half wave resistive load, $T_{case} = 80^{\circ}C$	240	A
$I_{T(RMS)}$	RMS value	$T_{case} = 80^{\circ}C$	380	A
$I_T$	Continuous (direct) on-state current	$T_{case} = 80^{\circ}C$	295	A

# ACR400SE

## SURGE RATINGS

Symbol	Parameter	Conditions	Max.	Units
$I_{TSM}$	Surge (non-repetitive) on-state current	10ms half sine; $T_{case} = 125^{\circ}C$	6.0	kA
$I^2t$	$I^2t$ for fusing	$V_R = 0$	$810 \times 10^3$	A <sup>2</sup> s

## THERMAL AND MECHANICAL DATA

Symbol	Parameter	Conditions	Min.	Max.	Units	
$R_{th(j-c)}$	Thermal resistance - junction to case	Double side cooled	dc	-	0.041	$^{\circ}C/W$
		Single side cooled	Anode dc	-	0.074	$^{\circ}C/W$
			Cathode dc	-	0.092	$^{\circ}C/W$
$R_{th(c-h)}$	Thermal resistance - case to heatsink	Clamping force 7.0kN with mounting compound	Double side	-	0.018	$^{\circ}C/W$
			Single side	-	0.036	$^{\circ}C/W$
$T_{vj}$	Virtual junction temperature	On-state (conducting)		-	135	$^{\circ}C$
		Reverse (blocking)		-	125	$^{\circ}C$
$T_{stg}$	Storage temperature range		-55	125	$^{\circ}C$	
-	Clamping force		6.0	8.0	kN	

## DYNAMIC CHARACTERISTICS

Symbol	Parameter	Conditions	Min.	Max.	Units
$V_{TM}$	Maximum on-state voltage	At 1500A peak, $T_{case} = 25^{\circ}C$	-	3.25	V
$I_{RRM}/I_{DRM}$	Peak reverse and off-state current	At $V_{RRM}/V_{DRM}$ , $T_{case} = 125^{\circ}C$	-	60	mA
dV/dt	Maximum linear rate of rise of off-state voltage	To $V_{DRM}$ $T_j = 125^{\circ}C$ , Gate open circuit	-	1000	V/ $\mu$ s
di/dt	Rate of rise of on-state current	From $V_{DRM}$ to 125A Gate source 15V, 15 $\Omega$ $t_r = 50ns$ .	-	500	A/ $\mu$ s
$V_{T(To)}$	Threshold voltage	At $T_{vj} = 125^{\circ}C$	-	1.8	V
$r_T$	On-state slope resistance	At $T_{vj} = 125^{\circ}C$	-	0.9	m $\Omega$
$I_L$	Latching current	-	500	-	mA
$I_H$	Holding current	-	100	-	mA
$t_d$	Delay time	$V_D = 300V$ , gate source = 15V, 15 $\Omega$	-	800	ns
$t_q$	Turn-off time	$I_T = 500A$ , square wave 50 $\mu$ s pulse, $T_j = 120^{\circ}C$ , $dI_{RR}/dt = 50A/\mu$ s, $dV/dt = 500V/\mu$ s to 75% $V_{DRM}$ .	-	10.0	$\mu$ s

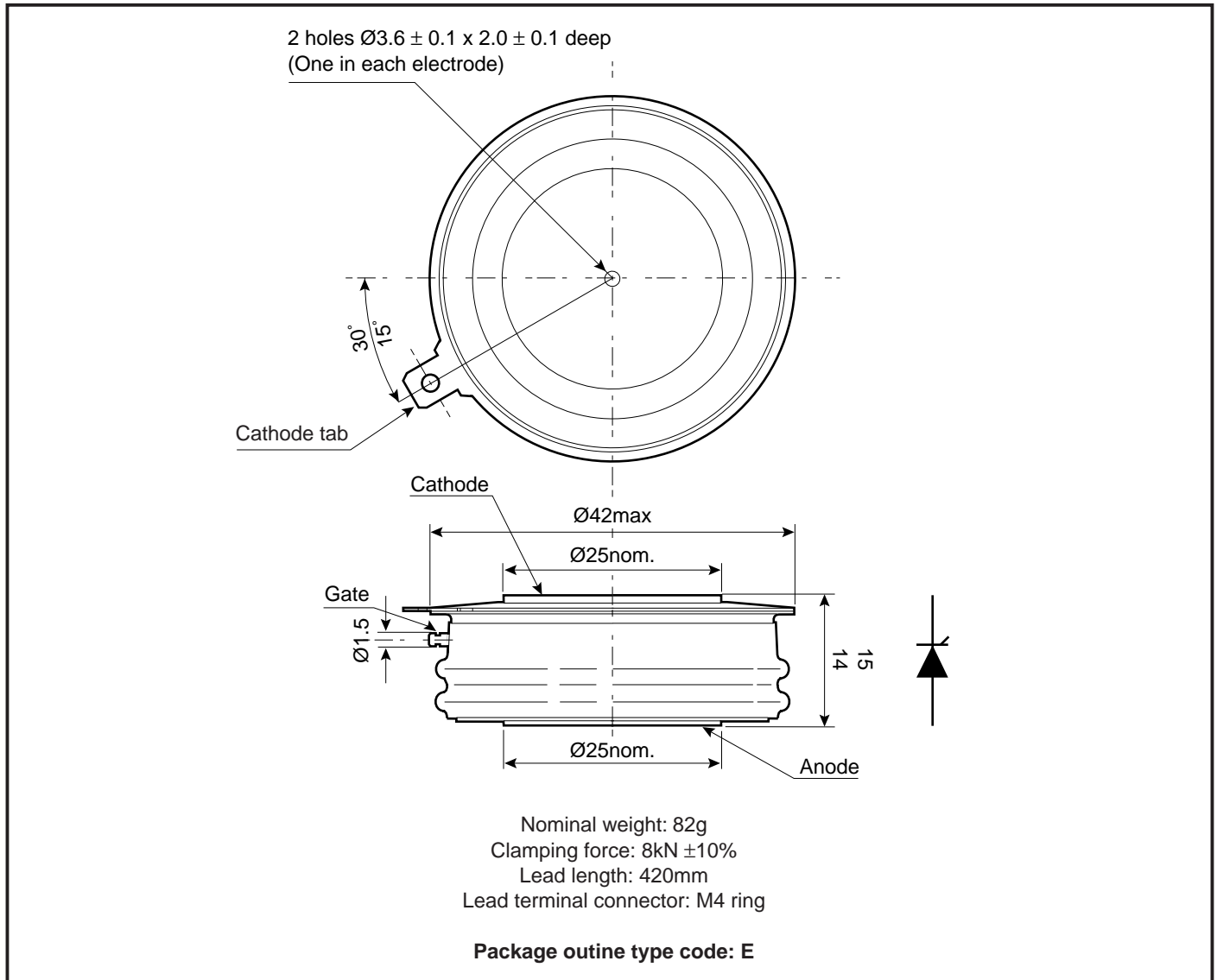
## GATE TRIGGER CHARACTERISTICS AND RATINGS

Symbol	Parameter	Conditions	Typ.	Max.	Units	
$V_{GT}$	Gate trigger voltage	$V_{DWM} = 12V$ , $R_L = 30\Omega$ , $T_{case} = 25^{\circ}C$	-	5	V	
$I_{GT}$	Gate trigger current	$V_{DWM} = 12V$ , $R_L = 30\Omega$ , $T_{case} = 25^{\circ}C$	-	500	mA	
$V_{FGM}$	Peak forward gate voltage	-	-	40	V	
$V_{RGM}$	Peak reverse gate voltage	-	-	10	V	
$I_{FGM}$	Peak forward gate current	-	-	10	A	
$P_{GM}$	Peak gate power	-	-	40	W	
$P_{G(AV)}$	Average gate power	Average time 10ms max	Forward	-	10	W
			Reverse	-	-	W

# ACR400SE

## PACKAGE DETAILS

For further package information, please contact your local Customer Service Centre. All dimensions in mm, unless stated otherwise. DO NOT SCALE.



## ASSOCIATED PUBLICATIONS

Title	Application Note
	Number
Calculating the junction temperature or power semiconductors	AN4506
Gate triggering and the use of gate characteristics	AN4840
Recommendations for clamping power semiconductors	AN4839
The effect of temperature on thyristor performance	AN4870
Thyristor and diode measurement with a multi-meter	AN4853
Turn-on performance of thyristors in parallel	AN4999
Use of $V_{TO}$ , $r_T$ on-state characteristic	AN5001

## POWER ASSEMBLY CAPABILITY

The Power Assembly group was set up to provide a support service for those customers requiring more than the basic semiconductor, and has developed a flexible range of heatsink / clamping systems in line with advances in device types and the voltage and current capability of our semiconductors.

We offer an extensive range of air and liquid cooled assemblies covering the full range of circuit designs in general use today. The Assembly group continues to offer high quality engineering support dedicated to designing new units to satisfy the growing needs of our customers.

Using the up to date CAD methods our team of design and applications engineers aim to provide the Power Assembly Complete solution (PACs).

## DEVICE CLAMPS

Disc devices require the correct clamping force to ensure their safe operation. The PACs range offers a varied selection of pre-loaded clamps to suit all of our manufactured devices. This include cube clamps for single side cooling of 'T' 22mm

Clamps are available for single or double side cooling, with high insulation versions for high voltage assemblies.

Please refer to our application note on device clamping, AN4839

## HEATSINKS

Power Assembly has it's own proprietary range of extruded aluminium heatsinks. They have been designed to optimise the performance of our semiconductors. Data with respect to air natural, forced air and liquid cooling (with flow rates) is available on request.

For further information on device clamps, heatsinks and assemblies, please contact your nearest Sales Representative or the factory.



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**Preliminary Information:** The product is in design and development. The datasheet represents the product as it is understood but details may change.

**Advance Information:** The product design is complete and final characterisation for volume production is well in hand.

**No Annotation:** The product parameters are fixed and the product is available to datasheet specification.

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